



BAT54J / W / AW / CW / SW

SMALL SIGNAL SCHOTTKY DIODE

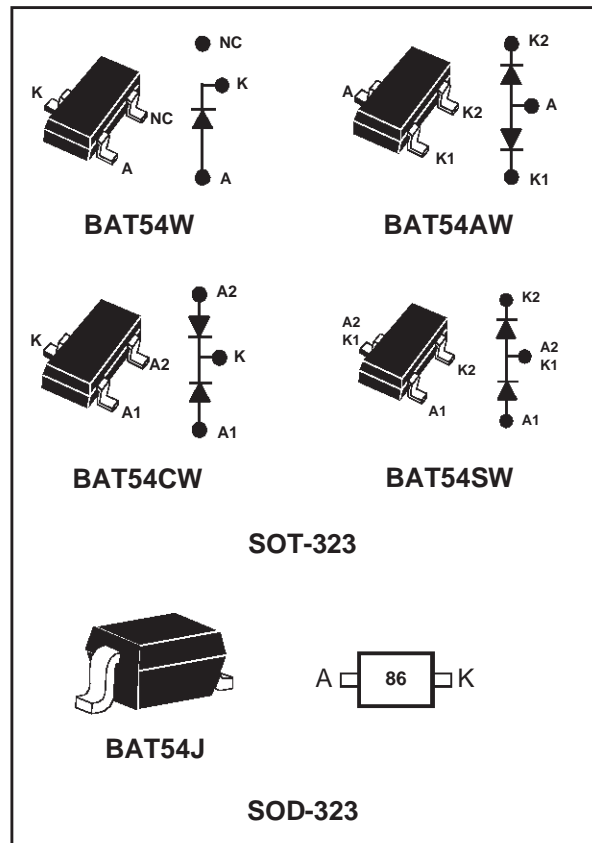
FEATURES AND BENEFITS

- VERY SMALL CONDUCTION LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- LOW FORWARD VOLTAGE DROP
- SURFACE MOUNT DEVICE

DESCRIPTION

Schottky barrier diodes encapsulated either in SOT-323 or SOD-323 small SMD packages.

Single and double diodes with different pinning are available.



ABSOLUTE RATINGS (limiting values)

| Symbol | Parameter | | Value | Unit |
|-----------|--|-----------------------|--------------|------------|
| V_{RRM} | Repetitive peak reverse voltage | | 30 | V |
| I_F | Continuous forward current | | 0.3 | A |
| I_{FSM} | Surge non repetitive forward current | $t_p=10ms$ sinusoidal | 1 | A |
| P_{tot} | Power dissipation (note 1) $T_{amb} = 25^\circ C$ | SOD-323 | 230 | mW |
| | | SOT-323 | | |
| T_{stg} | Maximum storage temperature range | | - 65 to +150 | $^\circ C$ |
| T_j | Maximum operating junction temperature * | | 150 | $^\circ C$ |
| T_L | Maximum temperature for soldering during 10s | | 260 | $^\circ C$ |

Note 1: for double diodes, P_{tot} is the total dissipation of both diodes

* : $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ thermal runaway condition for a diode on its own heatsink

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THERMAL RESISTANCE

| Symbol | Parameters | | Value | Unit |
|---------------|-------------------------|---------|-------|------|
| $R_{th(j-a)}$ | Junction to ambient (*) | SOD-323 | 550 | °C/W |
| | | SOT-323 | | °C/W |

(*) Mounted on epoxy board, with recommended pad layout.

STATIC ELECTRICAL CHARACTERISTICS (per diode)

| Symbol | Parameters | Tests conditions | | Min. | Typ. | Max. | Unit |
|------------|-------------------------|---------------------------|------------------------|------|------|------|---------------|
| V_F^* | Forward voltage drop | $T_j = 25^\circ\text{C}$ | $I_F = 0.1 \text{ mA}$ | | | 240 | mV |
| | | | $I_F = 1 \text{ mA}$ | | | 320 | |
| | | | $I_F = 10 \text{ mA}$ | | | 400 | |
| | | | $I_F = 30 \text{ mA}$ | | | 500 | |
| | | | $I_F = 100 \text{ mA}$ | | | 900 | |
| I_R^{**} | Reverse leakage current | $T_j = 25^\circ\text{C}$ | $V_R = 30 \text{ V}$ | | | 1 | μA |
| | | $T_j = 100^\circ\text{C}$ | | | | 100 | |

Pulse test : * $t_p = 380 \mu\text{s}$, $\delta < 2\%$

** $t_p = 5 \text{ ms}$, $\delta < 2\%$

DYNAMIC CHARACTERISTICS ($T_j = 25^\circ\text{C}$)

| Symbol | Parameters | Tests conditions | Min. | Typ. | Max. | Unit |
|----------|-----------------------|--|------|------|------|------|
| C | Junction capacitance | $T_j = 25^\circ\text{C}$ $V_R = 1 \text{ V}$ $F = 1 \text{ MHz}$ | | | 10 | pF |
| t_{rr} | Reverse recovery time | $I_F = 10 \text{ mA}$ $I_R = 10 \text{ mA}$ $T_j = 25^\circ\text{C}$ $I_{rr} = 1 \text{ mA}$ $R_L = 100 \Omega$ | | | 5 | ns |

Fig. 1-1: Forward voltage drop versus forward current (typical values, low level).

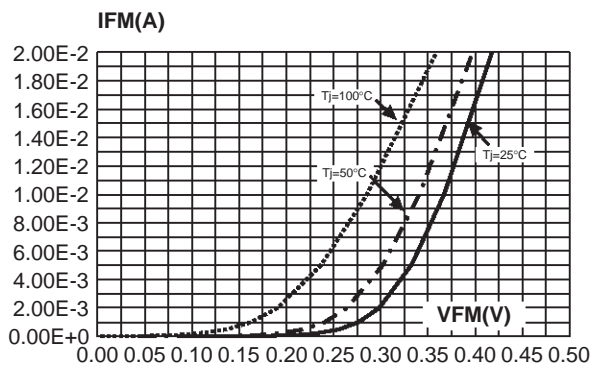


Fig. 1-2: Forward voltage drop versus forward current (typical values, high level).

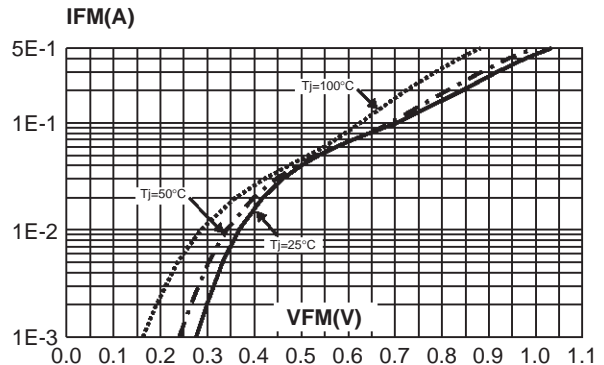


Fig. 2: Reverse leakage current versus reverse voltage applied (typical values).

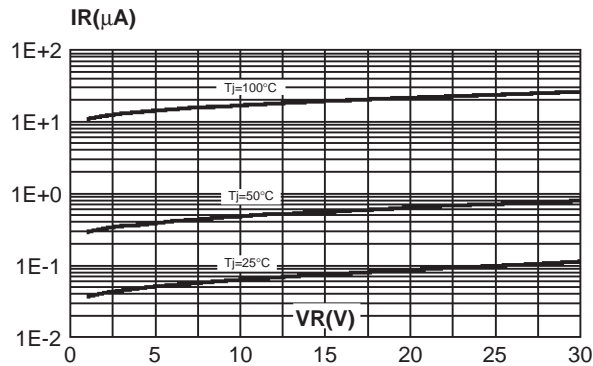


Fig. 3: Reverse leakage current versus junction temperature.

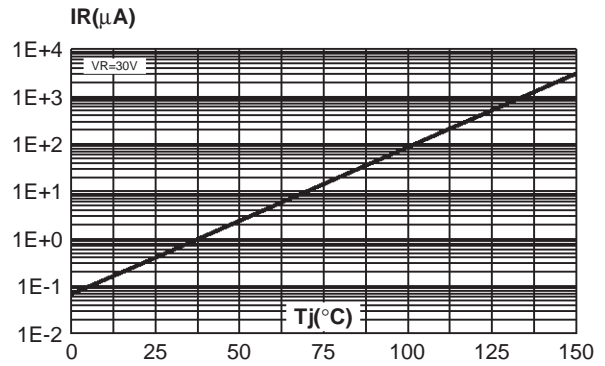


Fig. 4: Junction capacitance versus reverse voltage applied (typical values).

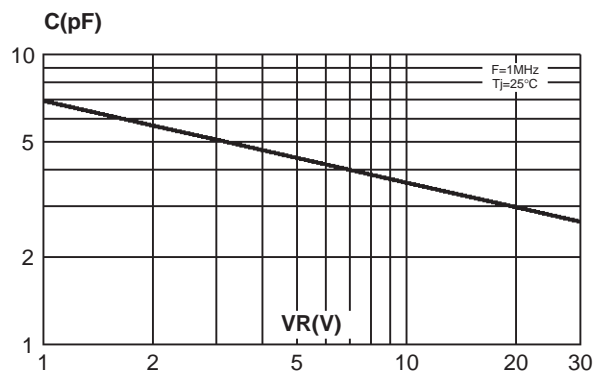


Fig. 5: Relative variation of thermal impedance junction to ambient versus pulse duration (epoxy FR4 with recommended pad layout, $e(Cu) = 35\mu m$)

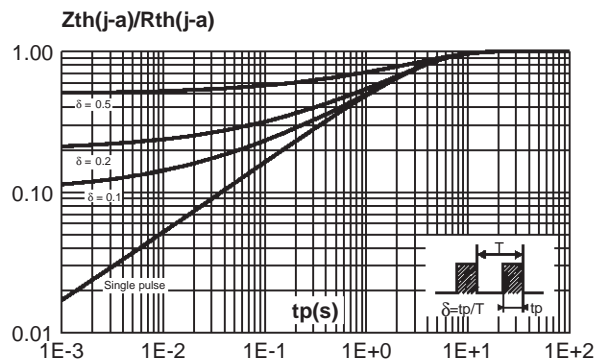
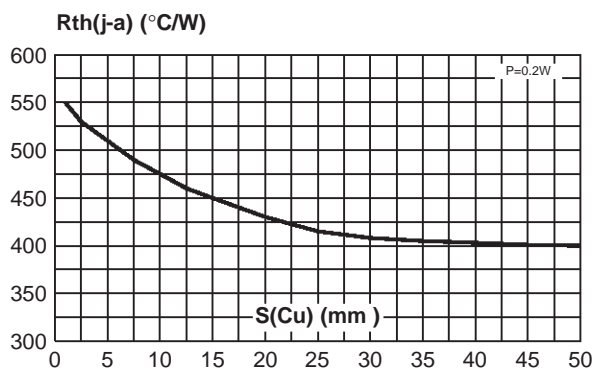
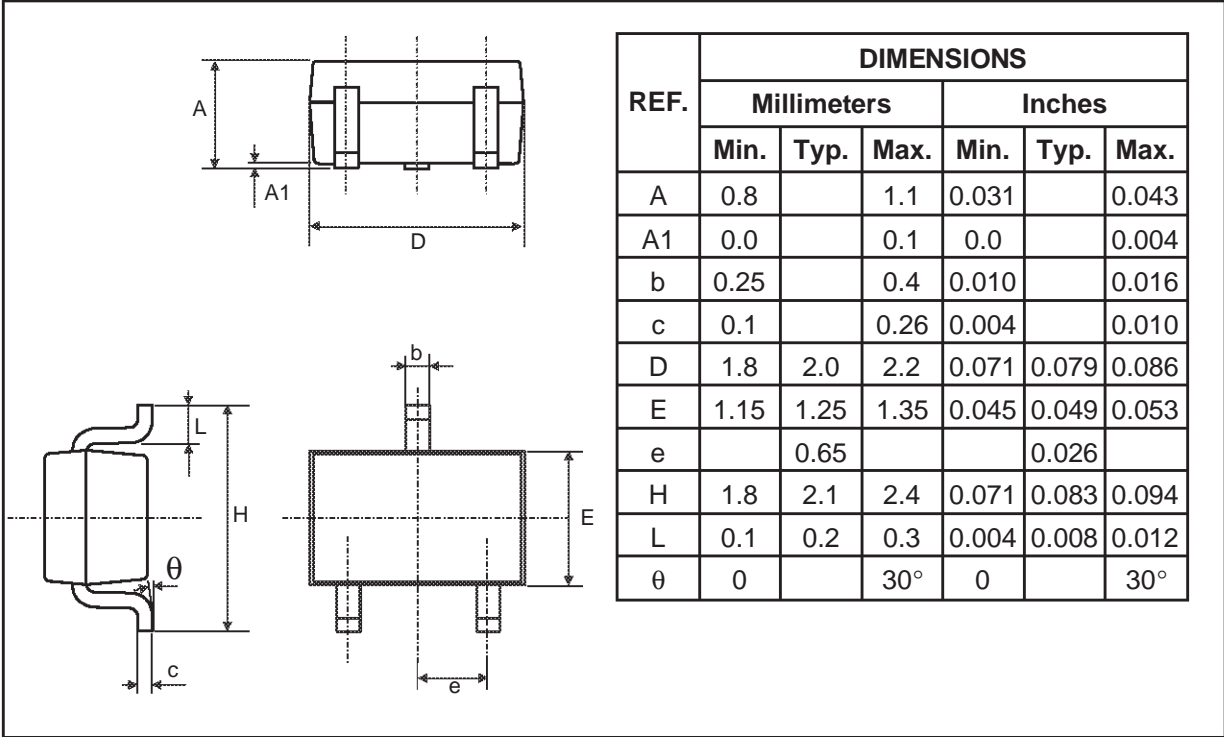


Fig. 6: Thermal resistance junction to ambient versus copper surface under each lead (Epoxy printed circuit board FR4, copper thickness: $35\mu m$.)

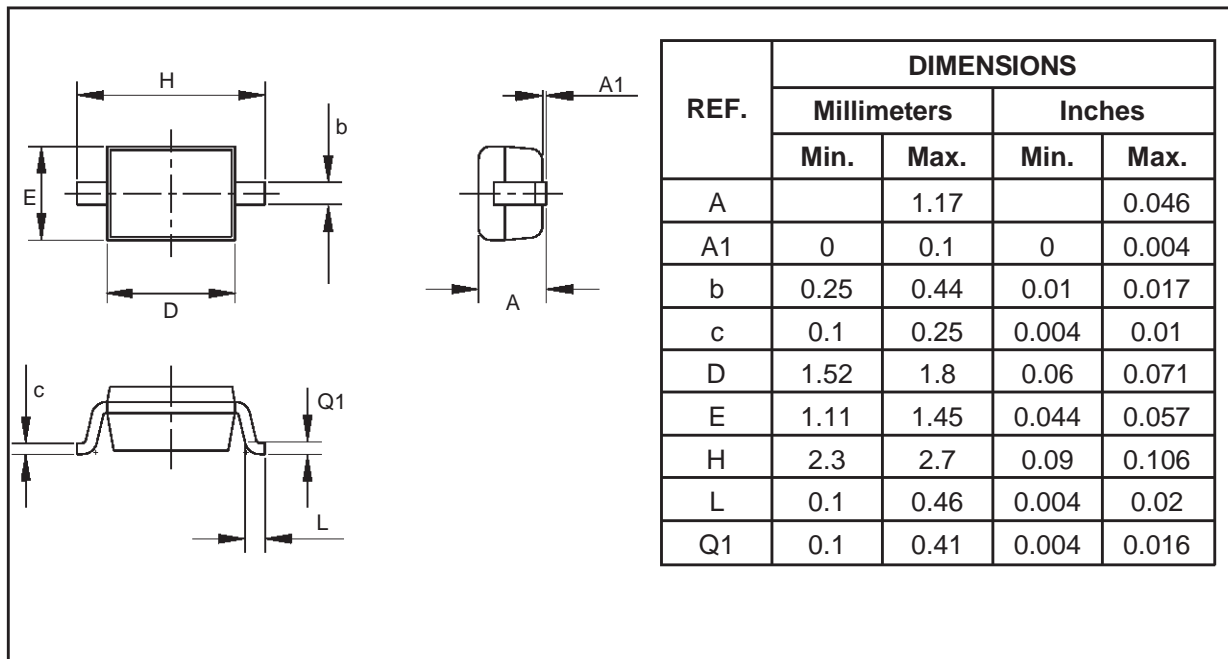


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PACKAGE MECHANICAL DATA
SOT-323



PACKAGE MECHANICAL DATA
SOD-323



| Ordering type | Marking | Package | Weight | Base qty | Delivery mode |
|---------------|---------|---------|--------|----------|---------------|
| BAT54W | D73 | SOT-323 | 0.006g | 3000 | Tape & reel |
| BAT54AW | D74 | SOT-323 | 0.006g | 3000 | Tape & reel |
| BAT54CW | D77 | SOT-323 | 0.006g | 3000 | Tape & reel |
| BAT54SW | D78 | SOT-323 | 0.006g | 3000 | Tape & reel |
| BAT54J | 86 | SOD-323 | 0.005g | 3000 | Tape & reel |

■ Epoxy meets UL94,V0

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